Email This Letter

03 April 2006

Stephen F Adam
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Los Altos, CA 94024-5805
s.adam@ieee.org

Re: P1693 - Modular Interconnect Packaging for Scalable Systems

Dear Stephen F:

I am pleased to inform you that on 30 March 2006 the IEEE-SA Standards Board approved the above referenced project until 31 December 2010. A copy of the file can be found on our website at http://standards.ieee.org/board/nes/projects/1693.pdf.

Now that your project has been approved, please forward a roster of participants involved in the development of this project. This request is in accordance with the IEEE-SA Operations Manual, Clause 5.1.2i under Duties of the Sponsor which states:

"Submit annually to the IEEE Standards Department an electronic roster of individuals participating on standards projects"

For your convenience, an Excel spreadsheet for your use has been posted on our website at http://standards.ieee.org/guides/par/roster.xls. Please forward this list to me via e-mail at j.haasz@ieee.org no later than 28 June 2006.

Please visit our website, IEEE Standards Development Online (http://standards.ieee.org/resources/development/index.html), for tools, forms and training to assist you in the standards development process. Also, we strongly recommend that a copy of your draft be sent to this office for review prior to the final vote by the working group to allow for a quick review by editorial staff before sponsor balloting begins.

If you should have any further questions, please contact me at 732-562-6367 or by email at j.haasz@ieee.org.

Sincerely,

Jodi Haasz
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International Stds Programs and Governance
Standards Activities
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CC: rhochberg@ieee.org, smann@bco-inc.com

PAR FORM

PAR Status: New PAR
PAR Approval Date: 30 March 2006
PAR Signature Page on File: Yes

1. Assigned Project Number: P1693

2. Sponsor Date of Request: 2006-02-17

3. Type of Document: Standard for

4. Title of Document:
Draft: Modular Interconnect Packaging for Scalable Systems

5. Life Cycle: Full-Use

6. Type of Project:
6a. Is this an update to an existing PAR? No

6b. The Project is a: New Standard

7. Working Group Information:
Name of Working Group: Modular Interconnect Packaging System Standard Subcommittee
Approximate Number of Expected Working Group Members:15

8. Contact information for Working Group Chair:
Name of Working Group Chair: Steve Mann
Telephone: +1 978 663 2525x126 **FAX:** +1 978 670 2939
Email: smann@bco-inc.com

9. Contact information for Co-Chair/Official Reporter, Project Editor or Document Custodian if different from the Working Group Chair:
Name of Co-Chair/Official Reporter, Project Editor or Document Custodian:
Telephone: **FAX:**
Email:

10. Contact information for Sponsoring Society or Standards Coordinating Committee:
Name of Sponsoring Society and Committee: IEEE Instrumentation and Measurement Society TC8-Automated Instrumentation
Name of Sponsoring Committee Chair: Michael Stora
Telephone: 973-299-8321 **FAX:** 973-299-9757
Email: mjs@sysintech.com
Name of Liaison Rep. (if different from the Sponsor Chair): Stephen F Adam
Telephone: 650-968-4900 **FAX:** 650-960-1398
Email: s.adam@ieee.org

Name of Co-Sponsoring Society and Committee:
Name of Co-Sponsoring Committee Chair:
Telephone: **FAX:**
Email:
Name of Liaison Rep. (if different from the Sponsor Chair):
Telephone: **FAX:**
Email:

11. The Type of ballot is: Individual Sponsor Ballot
Expected Date of Submission for Initial Sponsor Ballot: October 2007

12. Projected Completion Date for Submittal to RevCom: July 2008

Target Extension Request Information for a Modified PAR whose completion date is being extended past the original four-year life of the PAR:

13. Scope of Proposed Project:

This standard defines the electrical and mechanical specifications of a modular interconnect packaging system design for Automatic Test System (ATS). It specifically describes a building block approach based upon the integration of three elements: (1) the outer enclosure and the inner Eurocard standard mechanical chassis that forms the mechanical structure of the building block with alignment features to mate with other enclosures [building blocks]; (2) upgraded IEEE-1155 Standard for VME eXtensions for Instrumentation (VXI), that adds serial bus control to the backplane, a new pluggable virtual power source, and extends the VXI module length to directly couple with rear connectors of the IEEE-P1505 Receiver Fixture Interface [RFI] Standard; and (3) the segmentation of the IEEE-P1505 RFI Receiver Framework to match size of the basic building block while also meeting the intent of the IEEE-P1505.1 Common Test Interface (CTI) Pin Map Standard.

Is the completion of this document contingent upon the completion of another document? Yes

IEEE-P1505 Receiver Fixture Interface Standard - completed initial ballot satisfactorily- expect recirculation ballot next month and final approval by June 2006. IEEE-P1505.1 Common Test Interface Pin Map Standard - in final development phase. Expect to ballot at end of 2006 with approval by June 2007.

14. Purpose of Proposed Project:

The project establishes an integration standard for Automatic Test Systems that will permit integrators to quickly assemble systems under a plug&play architecture. It further defines for the VXI module suppliers an extended interconnect capability that will support direct plug-in of the VXI module to the RFI connector eliminating custom wire requirements. Building block segmentation that supports direct coupled VXI-RFI interconnectivity at the block level, permits scalability of the test system without cable integration of the building blocks.

15. Reason for the Proposed Project:

The standard eliminates cabling, improves performance, enhances repeatability between systems and eases calibration of the test system. The modular plug&play VXI module with direct coupled interconnect allows the integrator and user to quickly assemble (re)configure, upgrade, or replace the module within the ATS. By segmenting the RFI framework from a central location into scalable 12 slot elements, more VXI modules could be integrated under a direct interconnect scheme. Stakeholders include suppliers, integrators and users of modular interconnect packaging for scalable systems (MIPSS) for automatic test systems.

16. Intellectual Property:

a. **Has the IEEE-SA policy on intellectual property been presented to those responsible for preparing/submitting this PAR?** Yes 2006-02-10
b. **Is the sponsor aware of copyright permissions needed for this project?** No
c. **Is the sponsor aware of trademarks that apply to this project?** No
d. **Is the sponsor aware of possible registration activity related to this project?** No

17. Are there other documents or projects with a similar scope? No

Similar Scope Project Information:

18. Is there potential for this document (in part or in whole) to be adopted by another national , regional or international organization? Do not know at this time

If yes, the following questions must be answered:

Organization Name?

Technical Committee International Contact Information?

19. Will this project result in any health, safety, or environmental guidance that affects or applies to human health or safety? No

If yes, please explain:

20. Sponsor Information

a. **Is the scope of this project within the approved/scope/definition of the Sponsor's Charter?** Yes
If no, please explain:

b. **The Sponsor's procedures have been accepted by the IEEE-SA Standards Board Audit Committee?** Yes

21. Additional Explanatory Notes: (Item Number and Explanation)